



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

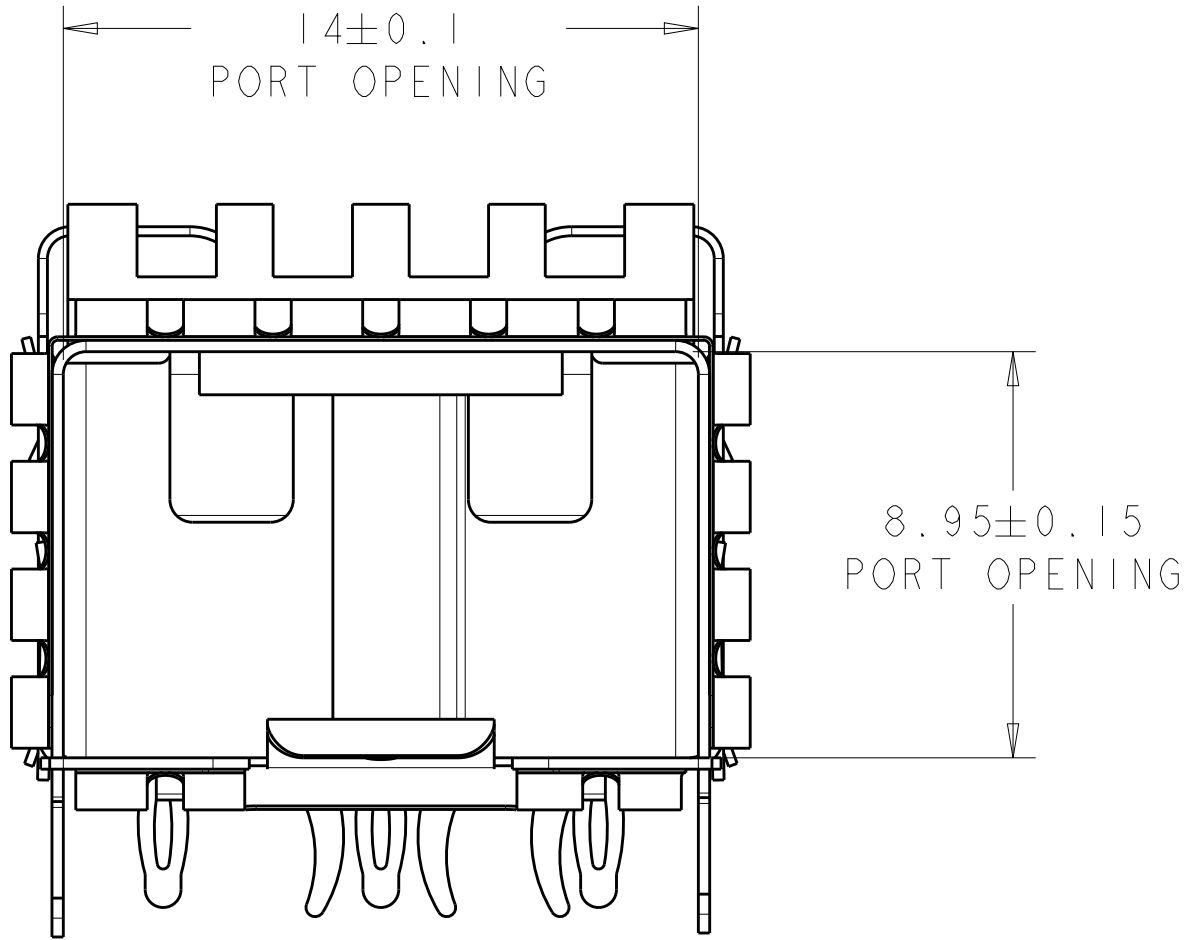
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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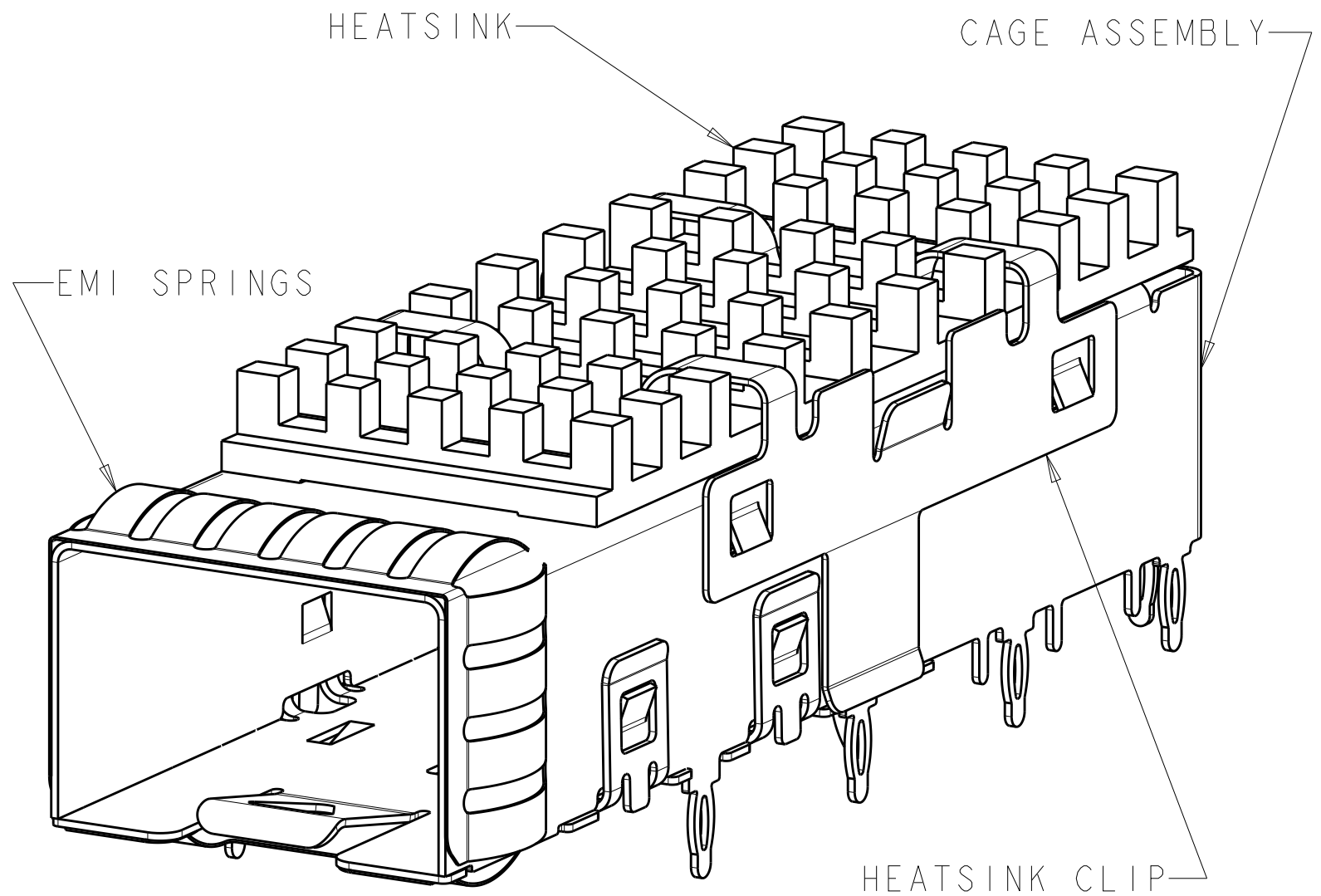
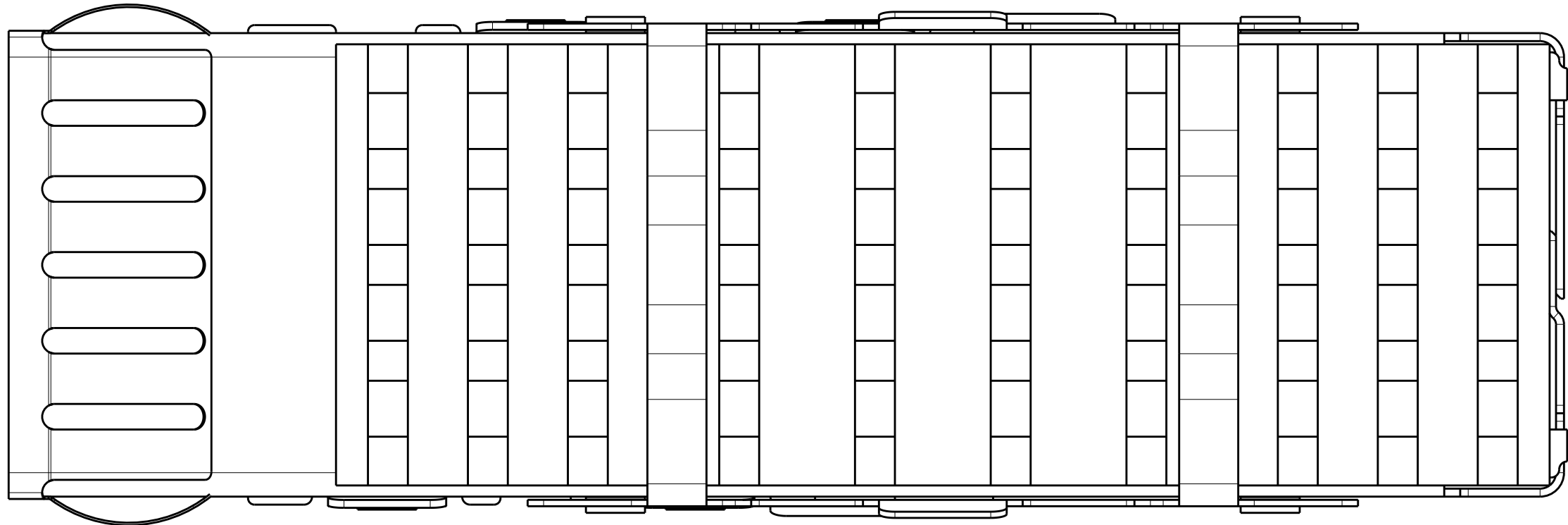


LOC	DIST	REVISIONS						
		P	LTR	DESCRIPTION	DATE	DWN	APVD	
GP	00	C		REVISED PER ECO-09-022874	20OCT2009	CR	MS	
		D		REVISED PER ECO-10-004036	26FEB2010	CJV	MRS	
		E		REVISED PER ECO-11-019224	09JAN2012	TX	AC	
		F		REVISED PER ECO-12-021462	10DEC2012	TX	AC	

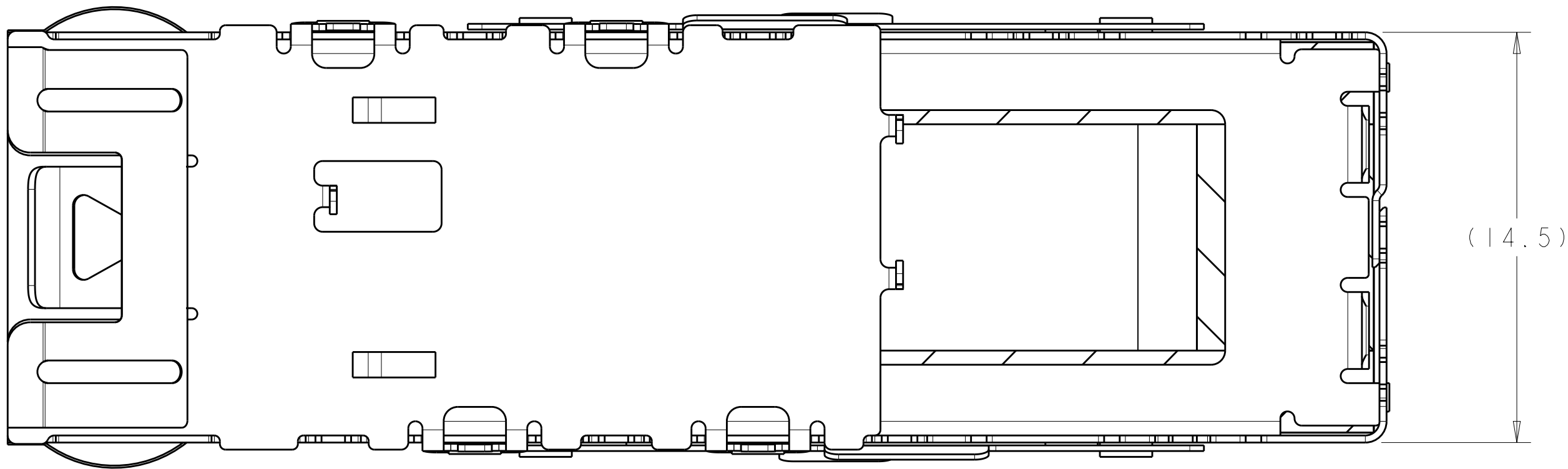
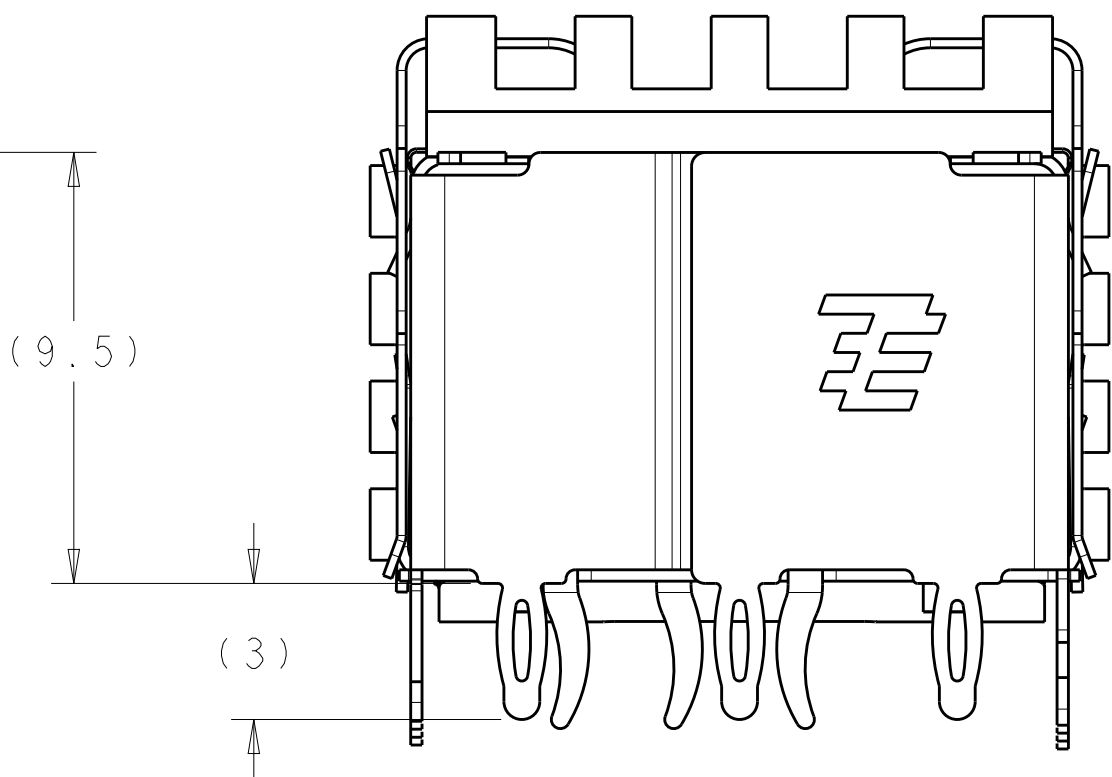
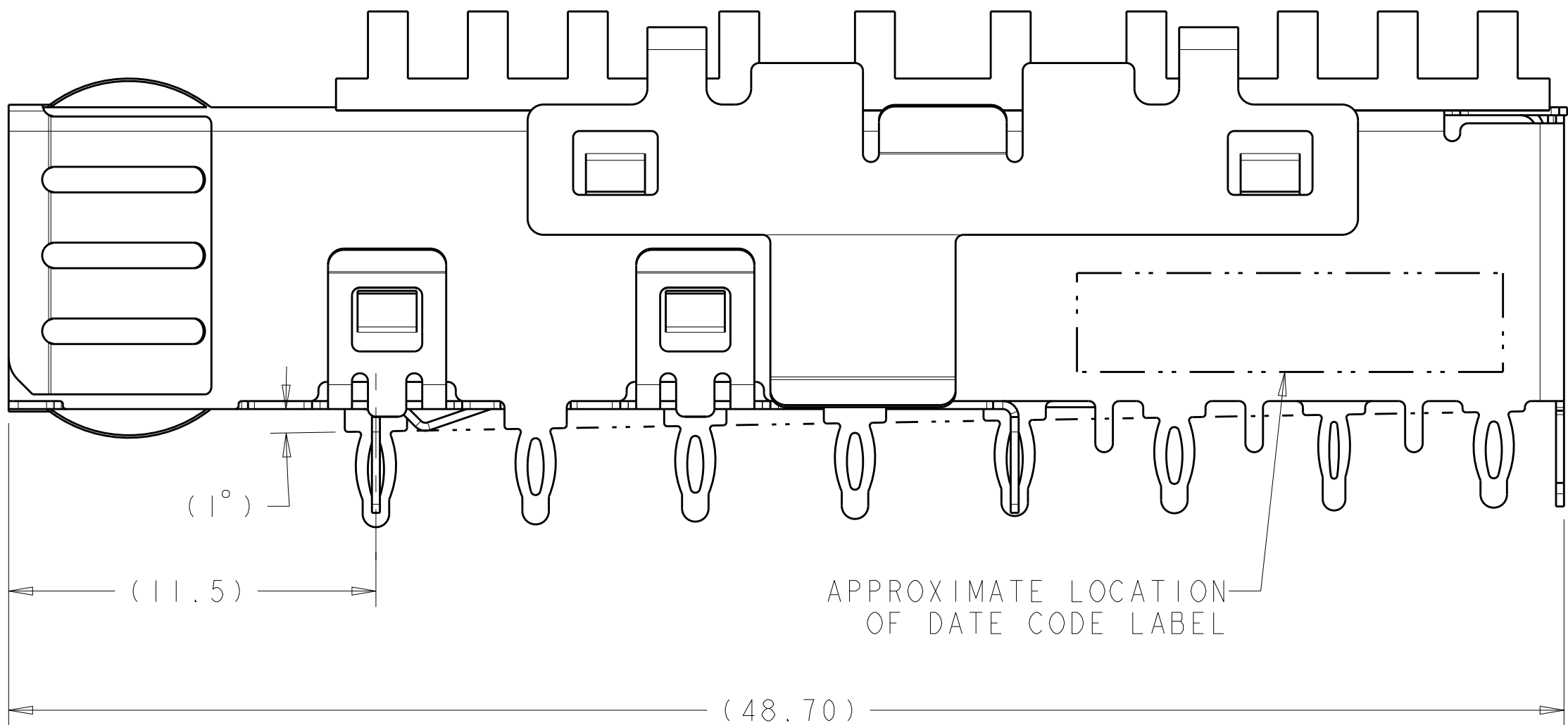
- 1 MATERIAL:
CAGE ASSEMBLY - NICKEL-SILVER ALLOY.
EMI SPRINGS - COPPER ALLOY.
HEATSINK - ALUMINUM.
HEATSINK CLIP - STAINLESS STEEL.
- 2 FINISH:
HEATSINK - ELECTROLESS NICKEL.
HEATSINK CLIP - PASSIVATE.
EMI SPRINGS - 0.8um MIN TIN OVER 0.8um MIN NICKEL
NON PLATED EDGES PERMISSIBLE.
3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 4 PADS AND VIAS CHASSIS GROUND.
- 5 DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
6. MINIMUM PC BOARD THICKNESS:
SINGLE SIDED = 1.50mm
- 7 REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR
RECOMMENDED DRILL HOLE DIAMETER AND PLATING
THICKNESS.



- 8 REFERENCE APPLICATION SPEC. 114-13120, HOLE C, FOR
RECOMMENDED DRILL HOLE DIAMETER AND PLATING
THICKNESS.
- 9 DIMENSIONS APPLIES PRIOR TO INSERTION OF SFP MODULE.
10. CAGE ASSEMBLY, HEATSINK CLIP AND HEATSINK SHIPPED
ASSEMBLED.
11. NOTE DELETED
- 12 REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR
RECOMMENDED DRILL HOLE DIAMETER AND PLATING
THICKNESS.

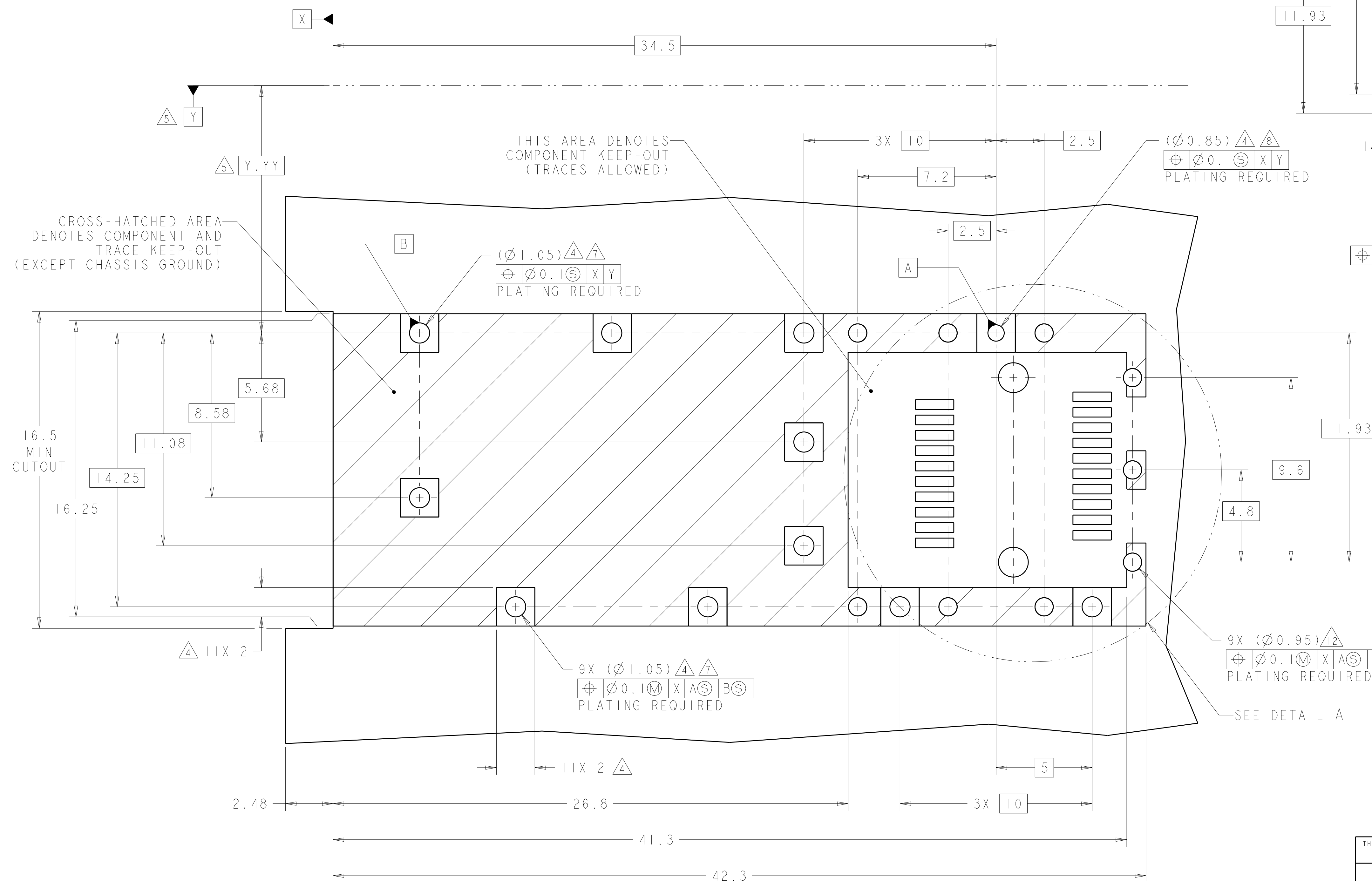
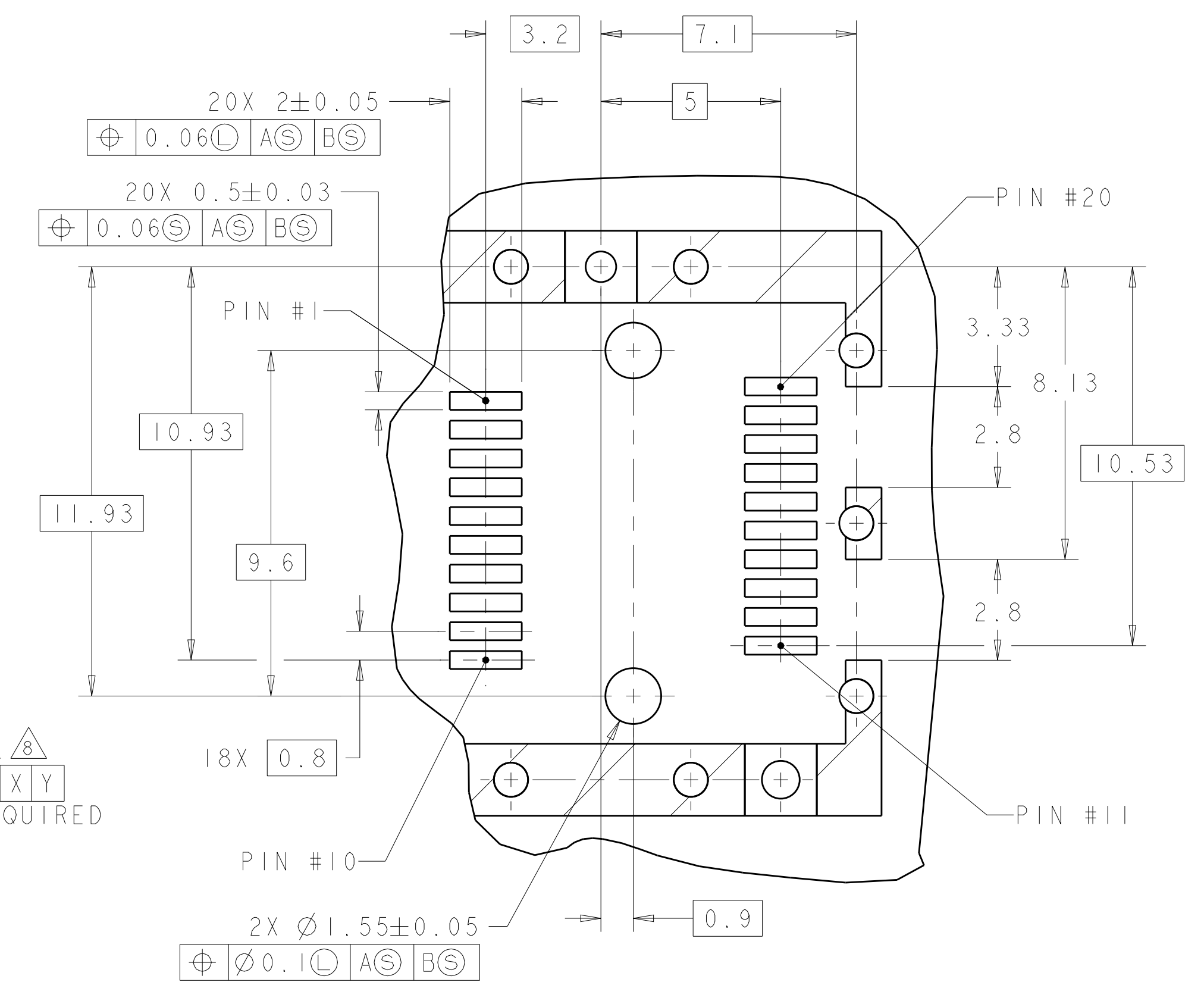



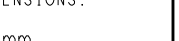
2007277-1
SCALE 5:1



2007277-1
PART
NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN M. SCHMITT 6AUG2007	TE Connectivity	
DIMENSIONS:		CHK M. SCHMITT 6AUG2007		
mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD B. WERTZ 6AUG2007	NAME	
	0 PLC ±0.1	PRODUCT SPEC	SFP+ 1X1 CAGE ASSEMBLY W/ HEATSINK, PCI, PRESS-FIT EXTERNAL EMI SPRING	
	1 PLC ±0.1	108-2364		
	2 PLC ±0.1	APPLICATION SPEC		
	3 PLC ±0.05	114-13120	SIZE CAGE CODE DRAWING NO	
	4 PLC ±0.05	WEIGHT	A100779C=2007277	
MATERIAL	FINISH	Customer Drawing	SCALE 6:1	SHEET 1 OF 2 REV F



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN M. SCHMITT 6AUG2007		 TE Connectivity	
		CHK M. SCHMITT 6AUG2007			
DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME	
mm		APPROVED B. WERTZ 6AUG2007		SFP+ 1X1 CAGE ASSEMBLY	
		0 PLC ±0.1		PRODUCT SPEC	
		1 PLC ±0.1		W/ HEATSINK, PCI, PRESS-FIT	
		2 PLC ±0.1		EXTERNAL EMI SPRING	
		3 PLC ±0.05		APPLICATION SPEC	
		4 PLC ±0.05		114-13120	
ANGLES		FINISH		SIZE CAGE CODE DRAWING NO	
MATERIAL		WEIGHT		RESTRICTED TO	
-		-		A1 00779 ©=2007277	
		Customer Drawing		SCALE 6:1 SHEET 2 of 2 REV F	